

**AMENDMENT TO THE SPECIFICATION:**

Please insert the following paragraph before the heading "Background of the Invention" of the patent application, as originally filed:

**CROSS-REFERENCE TO RELATED APPLICATIONS**

This application is a continuation-in-part of U.S. Patent Application No. 10/261,839, filed on September 30, 2002, and entitled "METHOD AND APPARATUS FOR DRYING SEMICONDUCTOR WAFER SURFACES USING A PLURALITY OF INLETS AND OUTLETS HELD IN CLOSE PROXIMITY TO THE WAFER SURFACES," from which priority under 35 U.S.C. § 120 is claimed.